

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application

Listing of Claims:

1-9 (cancelled)

10. (currently amended) A method for packaging an integrated circuit chip, said chip including active and passive surfaces with contact pads on said active surface, said method comprising the steps of:

providing a substrate, said substrate comprising:

a carrier tape;

a patterned metal layer having first and second surfaces and openings extending between said first and second surfaces, said second surface of said patterned metal layer removably attached to said carrier tape;

a first insulating layer covering said first surface of said patterned metal layer and portions of said carrier tape exposed in said openings in said patterned metal layer;

attaching said integrated circuit chip to said first insulating layer on said substrate;

encapsulating said chip; [[and]]

removing said carrier tape from said patterned metal layer to expose said second surface of said patterned metal layer[.]; and

applying a second insulating layer thinner than the carrier tape to the second surface of said patterned metal layer and uncovering a portion of the second surface of said patterned metal layer.

11. (canceled)

12. (currently amended) The method according to Claim [[11]] 10, further comprising the step of:

attaching solder balls to said second surface of said patterned metal layer exposed in said windows in said second insulating layer.

13. (cancelled)

14. (currently amended) The method according to Claim [[11]] 10, wherein said step of removing said carrier tape is preceded by the step of exposing said carrier tape to ultra-violet radiation.

15. (original) The method according to Claim 11, wherein said step of applying a second insulating layer comprises applying less than 30 μm of insulating layer to said second surface of said patterned metal layer.

16. (original) The method according to Claim 11, wherein said step of applying a second insulating layer comprises applying solder resist to said second surface of said patterned metal layer.

17. (currently amended) The method according to Claim [[11]] 10, wherein said step of providing a substrate with a first insulating layer comprises providing a substrate with a solder resist layer covering said first surface of said patterned metal layer.

18. (new) A method for packaging an integrated circuit chip, comprising:
providing an integrated circuit chip;
providing an insulating carrier tape with a patterned metal layer with a first side adhering to the insulating carrier tape;

positioning the integrated circuit chip over a second side of the metal layer and electrically connecting the integrated circuit chip to the metal pattern;
encapsulating the chip and the electrical connections;
removing the carrier tape to uncover the entire first side of the metal layer; and
then applying an insulating layer to the first side uncovering a portion of the first side of the patterned metal layer.

19. (new) The method of claim 18, in which the insulating layer is thinner than the insulating carrier tape.